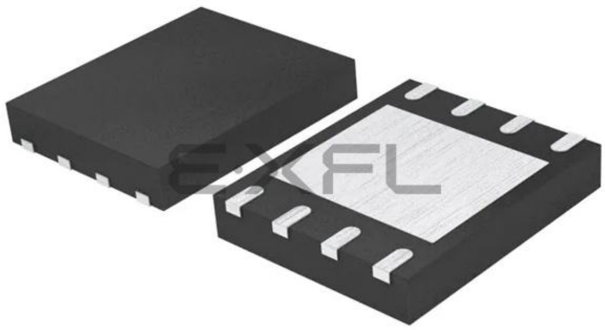


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	eZ8
Core Size	8-Bit
Speed	5MHz
Connectivity	IrDA, UART/USART
Peripherals	Brown-out Detect/Reset, LED, POR, PWM, WDT
Number of I/O	6
Program Memory Size	2KB (2K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-QFN (5x6)
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8f0213qb005sc

Overview

Zilog's Z8 Encore! XP® microcontroller unit (MCU) family of products are the first Zilog® microcontroller products based on the 8-bit eZ8 CPU core. Z8 Encore! XP F0823 Series products expand upon Zilog's extensive line of 8-bit microcontrollers. The Flash in-circuit programming capability allows for faster development time and program changes in the field. The new eZ8 CPU is upward compatible with existing Z8® instructions. The rich peripheral set of Z8 Encore! XP F0823 Series makes it suitable for a variety of applications including motor control, security systems, home appliances, personal electronic devices, and sensors.

Features

The key features of Z8 Encore! XP F0823 Series include:

- 5 MHz eZ8 CPU
- 1 KB, 2 KB, 4 KB, or 8 KB Flash memory with in-circuit programming capability
- 256 B, 512 B, or 1 KB register RAM
- 6 to 24 I/O pins depending upon package
- Internal precision oscillator (IPO)
- Full-duplex UART
- The universal asynchronous receiver/transmitter (UART) baud rate generator (BRG) can be configured and used as a basic 16-bit timer
- Infrared data association (IrDA)-compliant infrared encoder/decoders, integrated with UART
- Two enhanced 16-bit timers with capture, compare, and PWM capability
- Watchdog Timer (WDT) with dedicated internal RC oscillator
- On-Chip Debugger (OCD)
- Optional 8-channel, 10-bit Analog-to-Digital Converter (ADC)
- On-Chip analog comparator
- Up to 20 vectored interrupts
- Direct LED drive with programmable drive strengths
- Voltage Brownout (VBO) protection
- Power-On Reset (POR)

vector address. Following Stop Mode Recovery, the STOP bit in the Watchdog Timer Control Register is set to 1. Table 11 lists the Stop Mode Recovery sources and resulting actions. The section following the table provides more detailed information on each of the Stop Mode Recovery sources.

Table 11. Stop Mode Recovery Sources and Resulting Action

Operating Mode	Stop Mode Recovery Source	Action
STOP mode	Watchdog Timer time-out when configured for Reset	Stop Mode Recovery
	Watchdog Timer time-out when configured for interrupt	Stop Mode Recovery followed by interrupt (if interrupts are enabled)
	Data transition on any GPIO port pin enabled as a Stop Mode Recovery source	Stop Mode Recovery
	Assertion of external $\overline{\text{RESET}}$ Pin	System Reset
	Debug Pin driven Low	System Reset

Stop Mode Recovery Using Watchdog Timer Time-Out

If the Watchdog Timer times out during STOP mode, the device undergoes a Stop Mode Recovery sequence. In the Watchdog Timer Control register, the WDT and STOP bits are set to 1. If the Watchdog Timer is configured to generate an interrupt upon time-out and Z8 Encore! XP® F0823 Series device is configured to respond to interrupts, the eZ8 CPU services the Watchdog Timer interrupt request following the normal Stop Mode Recovery sequence.

Stop Mode Recovery Using a GPIO Port Pin Transition

Each of the GPIO port pins can be configured as a Stop Mode Recovery input source. On any GPIO pin enabled as a Stop Mode Recovery source, a change in the input pin value (from High to Low or from Low to High) initiates Stop Mode Recovery.

Note: *The SMR pulses shorter than specified does not trigger a recovery. When this happens, the STOP bit in the Reset Status (RSTSTAT) register is set to 1.*

Caution: *In STOP mode, the GPIO Port Input Data registers (PxIN) are disabled. The Port Input Data registers record the port transition only if the signal stays on the port pin through the end of the Stop Mode Recovery delay. As a result, short pulses on the port pin can initiate Stop Mode Recovery without being written to the Port Input Data register or without initiating an interrupt (if enabled for that pin).*

Table 54. Timer 0–1 PWM Low Byte Register (TxPWML)

BITS	7	6	5	4	3	2	1	0
FIELD	PWML							
RESET	0	0	0	0	0	0	0	0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
ADDR	F05H, F0DH							

PWMH and PWML—Pulse-Width Modulator High and Low Bytes
These two bytes, {PWMH[7:0], PWML[7:0]}, form a 16-bit value that is compared to the current 16-bit timer count. When a match occurs, the PWM output changes state. The PWM output value is set by the TPOL bit in the Timer Control Register (TxCTL1) register.

The TxPWMH and TxPWML registers also store the 16-bit captured timer value when operating in CAPTURE or CAPTURE/COMPARE modes.

Timer 0–1 Control Registers

Time 0–1 Control Register 0

The Timer Control Register 0 (TxCTL0) and Timer Control Register 1 (TxCTL1) determine the timer operating mode. It also includes a programmable PWM deadband delay, two bits to configure timer interrupt definition, and a status bit to identify if the most recent timer interrupt is caused by an input Capture event.

Table 55. Timer 0–1 Control Register 0 (TxCTL0)

BITS	7	6	5	4	3	2	1	0
FIELD	TMODEHI	TICONFIG		Reserved	PWMD			INPCAP
RESET	0	0	0	0	0	0	0	0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
ADDR	F06H, F0EH							

TMODEHI—Timer Mode High Bit
This bit along with the TMODE field in TxCTL1 register determines the operating mode of the timer. This is the most-significant bit of the Timer mode selection value. See the TxCTL1 register description for more details.

TICONFIG—Timer Interrupt Configuration
This field configures timer interrupt definition.

ONE-SHOT Mode

When the timer is disabled, the Timer Output signal is set to the value of this bit. When the timer is enabled, the Timer Output signal is complemented upon timer Reload.

CONTINUOUS Mode

When the timer is disabled, the Timer Output signal is set to the value of this bit. When the timer is enabled, the Timer Output signal is complemented upon timer Reload.

COUNTER Mode

If the timer is enabled the Timer Output signal is complemented after timer reload.

0 = Count occurs on the rising edge of the Timer Input signal
1 = Count occurs on the falling edge of the Timer Input signal

PWM SINGLE OUTPUT Mode

0 = Timer Output is forced Low (0) when the timer is disabled. When enabled, the Timer Output is forced High (1) upon PWM count match and forced Low (0) upon Reload.
1 = Timer Output is forced High (1) when the timer is disabled. When enabled, the Timer Output is forced Low (0) upon PWM count match and forced High (1) upon Reload.

CAPTURE Mode

0 = Count is captured on the rising edge of the Timer Input signal
1 = Count is captured on the falling edge of the Timer Input signal

COMPARE Mode

When the timer is disabled, the Timer Output signal is set to the value of this bit. When the timer is enabled, the Timer Output signal is complemented upon timer Reload.

GATED Mode

0 = Timer counts when the Timer Input signal is High (1) and interrupts are generated on the falling edge of the Timer Input.
1 = Timer counts when the Timer Input signal is Low (0) and interrupts are generated on the rising edge of the Timer Input.

Figure 20. Flash Memory Arrangement

Flash Information Area

The Flash information area is separate from program memory and is mapped to the address range FE00H to FFFFH. Not all these addresses are accessible. Factory trim values for the analog peripherals are stored here. Factory calibration data for the ADC is also stored here.

Operation

The Flash Controller programs and erases Flash memory. The Flash Controller provides the proper Flash controls and timing for Byte Programming, Page Erase, and Mass Erase of Flash memory.

The Flash Controller contains several protection mechanisms to prevent accidental programming or erasure. These mechanism operate on the page, sector and full-memory levels.

The Flowchart in Figure 21 displays basic Flash Controller operation. The following subsections provide details about the various operations (Lock, Unlock, Byte Programming, Page Protect, Page Unprotect, Page Select Page Erase, and Mass Erase) displayed in Figure 21.

Flash Sector Protect Register

The Flash Sector Protect (FPROT) register is shared with the Flash Page Select Register. When the Flash Control Register is written with 73H followed by 5EH, the next write to this address targets the Flash Sector Protect Register. In all other cases, it targets the Flash Page Select Register.

This register selects one of the 8 available Flash memory sectors to be protected. The reset state of each Sector Protect bit is an unprotected state. After a sector is protected by setting its corresponding register bit, it cannot be unprotected (the register bit cannot be cleared) without powering down the device.

Table 82. Flash Sector Protect Register (FPROT)

BITS	7	6	5	4	3	2	1	0
FIELD	SPROT7	SPROT6	SPROT5	SPROT4	SPROT3	SPROT2	SPROT1	SPROT0
RESET	0	0	0	0	0	0	0	0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
ADDR	FF9H							

SPROT7-SPROT0—Sector Protection
Each bit corresponds to a 512 bytes Flash sector. For the Z8F08x3 devices, the upper 3 bits must be zero. For the Z8F04x3 devices all bits are used. For the Z8F02x3 devices, the upper 4 bits are unused. For the Z8F01x3 devices, the upper 6 bits are unused.

Flash Frequency High and Low Byte Registers

The Flash Frequency High (FFREQH) and Low Byte (FFREQL) registers combine to form a 16-bit value, FFREQ, to control timing for Flash program and erase operations. The 16-bit binary Flash Frequency value must contain the system clock frequency (in kHz) and is calculated using the following equation:

$$\text{FFREQ}[15:0] = \{\text{FFREQH}[7:0],\text{FFREQL}[7:0]\} = \frac{\text{System Clock Frequency}}{1000}$$

! Caution: *The Flash Frequency High and Low Byte registers must be loaded with the correct value to ensure proper operation of the device. Also, Flash programming and erasure is not supported for system clock frequencies below 20 kHz or above 20 MHz.*

On-Chip Debugger Commands

The host communicates to the OCD by sending OCD commands using the DBG interface. During normal operation, only a subset of the OCD commands are available. In DEBUG mode, all OCD commands become available unless the user code and control registers are protected by programming the Flash Read Protect Option bit (FRP). The Flash Read Protect Option bit prevents the code in memory from being read out of Z8 Encore! XP® F0823 Series products. When this option is enabled, several of the OCD commands are disabled. Table 99 on page 162 is a summary of the OCD commands. Each OCD command is described in further detail in the bulleted list following this table. Table 99 on page 162 also indicates those commands that operate when the device is not in DEBUG mode (normal operation) and those commands that are disabled by programming the Flash Read Protect Option bit.

Debug Command	Command Byte	Enabled when NOT in DEBUG mode?	Disabled by Flash Read Protect Option Bit
Read OCD Revision	00H	Yes	–
Reserved	01H	–	–
Read OCD Status Register	02H	Yes	–
Read Runtime Counter	03H	–	–
Write OCD Control Register	04H	Yes	Cannot clear DBGMODE bit.
Read OCD Control Register	05H	Yes	–
Write Program Counter	06H	–	Disabled.
Read Program Counter	07H	–	Disabled.
Write Register	08H	–	Only writes of the Flash Memory Control registers are allowed. Additionally, only the Mass Erase command is allowed to be written to the Flash Control register.
Read Register	09H	–	Disabled.
Write Program Memory	0AH	–	Disabled.
Read Program Memory	0BH	–	Disabled.
Write Data Memory	0CH	–	Yes.
Read Data Memory	0DH	–	–
Read Program Memory CRC	0EH	–	–
Reserved	0FH	–	–
Step Instruction	10H	–	Disabled.

- **Read Program Memory CRC (0EH)**—The Read Program Memory Cyclic Redundancy Check (CRC) command computes and returns the CRC of Program Memory using the 16-bit CRC-CCITT polynomial. If the device is not in DEBUG mode, this command returns FFFFH for the CRC value. Unlike most other OCD Read commands, there is a delay from issuing of the command until the OCD returns the data. The OCD reads the Program Memory, calculates the CRC value, and returns the result. The delay is a function of the Program Memory size and is approximately equal to the system clock period multiplied by the number of bytes in the Program Memory.

```
DBG ← 0EH
DBG → CRC[15:8]
DBG → CRC[7:0]
```

- **Step Instruction (10H)**—The Step Instruction command steps one assembly instruction at the current Program Counter (PC) location. If the device is not in DEBUG mode or the Flash Read Protect Option bit is enabled, the OCD ignores this command.

```
DBG ← 10H
```

- **Stuff Instruction (11H)**—The Stuff Instruction command steps one assembly instruction and allows specification of the first byte of the instruction. The remaining 0-4 bytes of the instruction are read from Program Memory. This command is useful for stepping over instructions where the first byte of the instruction has been overwritten by a Breakpoint. If the device is not in DEBUG mode or the Flash Read Protect Option bit is enabled, the OCD ignores this command.

```
DBG ← 11H
DBG ← opcode[7:0]
```

- **Execute Instruction (12H)**—The Execute Instruction command allows sending an entire instruction to be executed to the eZ8 CPU. This command can also step over breakpoints. The number of bytes to send for the instruction depends on the opcode. If the device is not in DEBUG mode or the Flash Read Protect Option bit is enabled, this command reads and discards one byte.

```
DBG ← 12H
DBG ← 1-5 byte opcode
```

On-Chip Debugger Control Register Definitions

OCD Control Register

The OCD Control register controls the state of the OCD. This register is used to enter or exit DEBUG mode and to enable the BRK instruction. It also resets Z8 Encore! XP® F0823 Series device.

INTEN—Internal Precision Oscillator Enable
1 = Internal precision oscillator is enabled
0 = Internal precision oscillator is disabled

Reserved—R/W bits must be 0 during writes; 0 when read

WDTEN—Watchdog Timer Oscillator Enable
1 = Watchdog Timer oscillator is enabled
0 = Watchdog Timer oscillator is disabled

POFEN—Primary Oscillator Failure Detection Enable
1 = Failure detection and recovery of primary oscillator is enabled
0 = Failure detection and recovery of primary oscillator is disabled

WDFEN—Watchdog Timer Oscillator Failure Detection Enable
1 = Failure detection of Watchdog Timer oscillator is enabled
0 = Failure detection of Watchdog Timer oscillator is disabled

SCKSEL—System Clock Oscillator Select
000 = Internal precision oscillator functions as system clock at 5.53 MHz
001 = Internal precision oscillator functions as system clock at 32 kHz
010 = Reserved
011 = Watchdog Timer oscillator functions as system clock
100 = External clock signal on PB3 functions as system clock
101 = Reserved
110 = Reserved
111 = Reserved

eZ8 CPU Instruction Set

Assembly Language Programming Introduction

The eZ8 CPU assembly language provides a means for writing an application program without concern for actual memory addresses or machine instruction formats. A program written in assembly language is called a source program. Assembly language allows the use of symbolic addresses to identify memory locations. It also allows mnemonic codes (opcodes and operands) to represent the instructions themselves. The opcodes identify the instruction while the operands represent memory locations, registers, or immediate data values.

Each assembly language program consists of a series of symbolic commands called statements. Each statement can contain labels, operations, operands, and comments.

Labels are assigned to a particular instruction step in a source program. The label identifies that step in the program as an entry point for use by other instructions.

The assembly language also includes assembler directives that supplement the machine instruction. The assembler directives, or pseudo-ops, are not translated into a machine instruction. Rather, the pseudo-ops are interpreted as directives that control or assist the assembly process.

The source program is processed (assembled) by the assembler to obtain a machine language program called the object code. The object code is executed by the eZ8 CPU. An example segment of an assembly language program is detailed in the following example.

Assembly Language Source Program Example

```
JP START          ; Everything after the semicolon is a comment.

START:            ; A label called 'START'. The first instruction (JP START) in this
                  ; example causes program execution to jump to the point within the
                  ; program where the START label occurs.

LD R4, R7         ; A Load (LD) instruction with two operands. The first operand,
                  ; Working Register R4, is the destination. The second operand,
                  ; Working Register R7, is the source. The contents of R7 is
                  ; written into R4.

LD 234H, #%01     ; Another Load (LD) instruction with two operands.
                  ; The first operand, Extended Mode Register Address 234H,
                  ; identifies the destination. The second operand, Immediate Data
                  ; value 01H, is the source. The value 01H is written into the
                  ; Register at address 234H.
```

Table 108. Bit Manipulation Instructions

Mnemonic	Operands	Instruction
BCLR	bit, dst	Bit Clear
BIT	p, bit, dst	Bit Set or Clear
BSET	bit, dst	Bit Set
BSWAP	dst	Bit Swap
CCF	—	Complement Carry Flag
RCF	—	Reset Carry Flag
SCF	—	Set Carry Flag
TCM	dst, src	Test Complement Under Mask
TCMX	dst, src	Test Complement Under Mask using Extended Addressing
TM	dst, src	Test Under Mask
TMX	dst, src	Test Under Mask using Extended Addressing

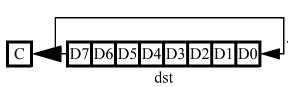
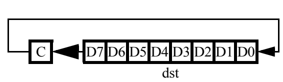
Table 109. Block Transfer Instructions

Mnemonic	Operands	Instruction
LDCI	dst, src	Load Constant to/from Program Memory and Auto-Increment Addresses
LDEI	dst, src	Load External Data to/from Data Memory and Auto-Increment Addresses

Table 110. CPU Control Instructions

Mnemonic	Operands	Instruction
ATM	—	Atomic Execution
CCF	—	Complement Carry Flag
DI	—	Disable Interrupts
EI	—	Enable Interrupts
HALT	—	HALT Mode
NOP	—	No Operation
RCF	—	Reset Carry Flag

Table 115. eZ8 CPU Instruction Summary (Continued)

Assembly Mnemonic	Symbolic Operation	Address Mode dst	Address Mode src	Opcode(s) (Hex)	Flags C	Z	S	V	D	H	Fetch Cycles	Instr. Cycles
OR dst, src	dst ← dst OR src	r	r	42	–	*	*	0	–	–	2	3
		r	Ir	43							2	4
		R	R	44							3	3
		R	IR	45							3	4
		R	IM	46							3	3
		IR	IM	47							3	4
ORX dst, src	dst ← dst OR src	ER	ER	48	–	*	*	0	–	–	4	3
		ER	IM	49							4	3
POP dst	dst ← @SP SP ← SP + 1	R		50	–	–	–	–	–	–	2	2
		IR		51							2	3
POPX dst	dst ← @SP SP ← SP + 1	ER		D8	–	–	–	–	–	–	3	2
PUSH src	SP ← SP – 1 @SP ← src	R		70	–	–	–	–	–	–	2	2
		IR		71							2	3
		IM		IF70							3	2
PUSHX src	SP ← SP – 1 @SP ← src	ER		C8	–	–	–	–	–	–	3	2
RCF	C ← 0			CF	0	–	–	–	–	–	1	2
RET	PC ← @SP SP ← SP + 2			AF	–	–	–	–	–	–	1	4
RL dst		R		90	*	*	*	*	–	–	2	2
		IR		91							2	3
RLC dst		R		10	*	*	*	*	–	–	2	2
		IR		11							2	3
Flags Notation:	* = Value is a function of the result of the operation. – = Unaffected X = Undefined				0 = Reset to 0 1 = Set to 1							

Electrical Characteristics

The data in this chapter is pre-qualification and pre-characterization and is subject to change. Additional electrical characteristics may be found in the individual chapters.

Absolute Maximum Ratings

Stresses greater than those listed in Table 117 may cause permanent damage to the device. These ratings are stress ratings only. Operation of the device at any condition outside those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. For improved reliability, tie unused inputs to one of the supply voltages (V_{DD} or V_{SS}).

Table 117. Absolute Maximum Ratings

Parameter	Minimum	Maximum	Units	Notes
Ambient temperature under bias	-40	+105	°C	
Storage temperature	-65	+150	°C	
Voltage on any pin with respect to V_{SS}	-0.3	+5.5	V	1
	-0.3	+3.9	V	2
Voltage on V_{DD} pin with respect to V_{SS}	-0.3	+3.6	V	
Maximum current on input and/or inactive output pin	-5	+5	µA	
Maximum output current from active output pin	-25	+25	mA	
8-pin Packages Maximum Ratings at 0 °C to 70 °C				
Total power dissipation		220	mW	
Maximum current into V_{DD} or out of V_{SS}		60	mA	
20-pin Packages Maximum Ratings at 0 °C to 70 °C				
Total power dissipation		430	mW	
Maximum current into V_{DD} or out of V_{SS}		120	mA	
28-pin Packages Maximum Ratings at 0 °C to 70 °C				
Total power dissipation		450	mW	

Table 118. DC Characteristics (Continued)

Symbol	Parameter	T_A = -40 °C to +105 °C (unless otherwise specified)			Units	Conditions
		Minimum	Typical	Maximum		
V_{OH2}	High Level Output Voltage	2.4	–	–	V	I_{OH} = -20 mA; V_{DD} = 3.3 V High Output Drive enabled.
I_{IH}	Input Leakage Current	–	$\pm$0.002	$\pm$5	µA	$V_{IN} = V_{DD}$ V_{DD} = 3.3 V;
I_{IL}	Input Leakage Current	–	$\pm$0.007	$\pm$5	µA	$V_{IN} = V_{SS}$ V_{DD} = 3.3 V;
I_{TL}	Tristate Leakage Current	–	–	$\pm$5	µA	
I_{LED}	Controlled Current Drive	1.8	3	4.5	mA	{AFS2,AFS1} = {0,0}
		2.8	7	10.5	mA	{AFS2,AFS1} = {0,1}
		7.8	13	19.5	mA	{AFS2,AFS1} = {1,0}
		12	20	30	mA	{AFS2,AFS1} = {1,1}
C_{PAD}	GPIO Port Pad Capacitance	–	8.0[2]	–	pF	
C_{XIN}	XIN Pad Capacitance	–	8.0[2]	–	pF	
C_{XOUT}	XOUT Pad Capacitance	–	9.5[2]	–	pF	
I_{PU}	Weak Pull-up Current	30	100	350	µA	V_{DD} = 3.0 V–3.6 V
V_{RAM}	RAM Data Retention Voltage	TBD			V	Voltage at which RAM retains static values; no reading or writing is allowed.

Notes
1. This condition excludes all pins that have on-chip pull-ups, when driven Low.
2. These values are provided for design guidance only and are not tested in production.

Table 123. Flash Memory Electrical Characteristics and Timing

Parameter	V_{DD} = 2.7 V to 3.6 V T_A = -40 °C to +105 °C (unless otherwise stated) Minimum	Typical	Maximum	Units	Notes
Flash Byte Read Time	100	–	–	ns	
Flash Byte Program Time	20	–	40	µs	
Flash Page Erase Time	10	–	–	ms	
Flash Mass Erase Time	200	–	–	ms	
Writes to Single Address Before Next Erase	–	–	2		
Flash Row Program Time	–	–	8	ms	Cumulative program time for single row cannot exceed limit before next erase. This parameter is only an issue when bypassing the Flash Controller.
Data Retention	100	–	–	years	25 °C
Endurance	10,000	–	–	cycles	Program/erase cycles

Table 124. Watchdog Timer Electrical Characteristics and Timing

Symbol	Parameter	V_{DD} = 2.7 V to 3.6 V T_A = -40 °C to +105 °C (unless otherwise stated) Minimum	Typical	Maximum	Units	Conditions
F_{WDT}	WDT Oscillator Frequency		10		kHz	
F_{WDT}	WDT Oscillator Error			$\pm$50	%	
T_{WDTCAL}	WDT Calibrated Timeout	0.98	1	1.02	s	V_{DD} = 3.3 V; T_A = 30 °C
		0.70	1	1.30	s	V_{DD} = 2.7 V to 3.6 V T_A = 0 °C to 70 °C
		0.50	1	1.50	s	V_{DD} = 2.7 V to 3.6 V T_A = -40 °C to +105 °C

UART Timing

Figure 32 and Table 130 provide timing information for UART pins for the case where CTS is used for flow control. The CTS to DE assertion delay (T1) assumes the transmit data register has been loaded with data prior to CTS assertion.

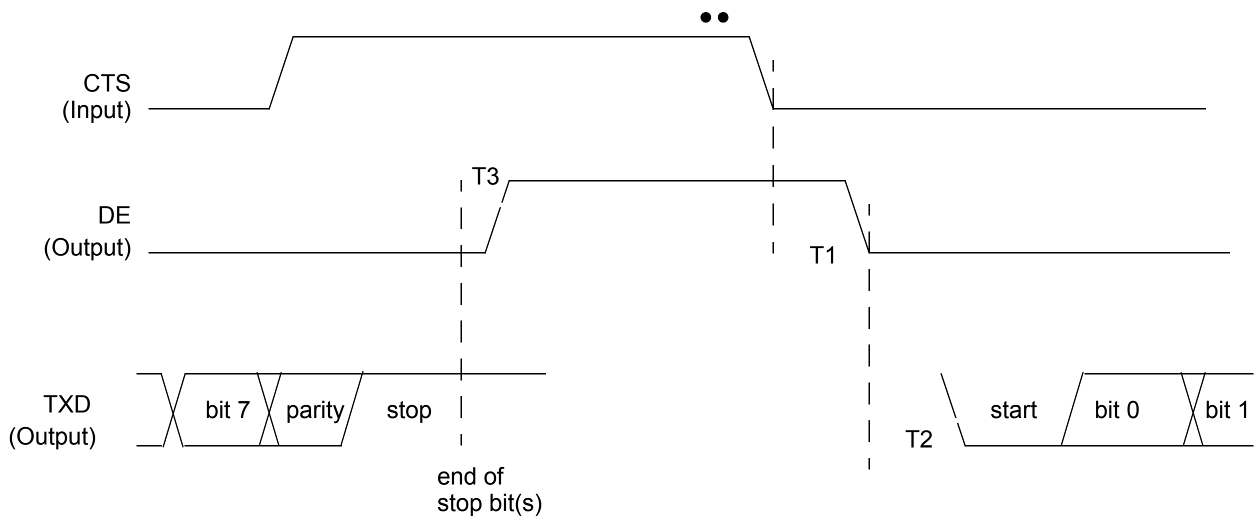
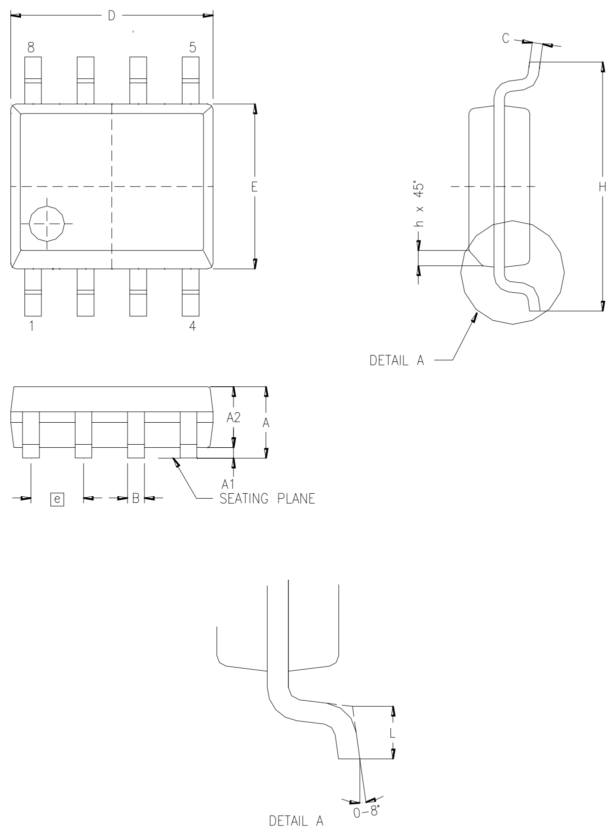


Figure 32. UART Timing With CTS

Table 130. UART Timing With CTS

		Delay (ns)	
Parameter	**Abbreviation**	**Minimum**	**Maximum**
UART			
T_1	CTS Fall to DE output delay	2 * XIN period	2 * XIN period + 1 bit time
T_2	DE assertion to TXD falling edge (start bit) delay	± 5	
T_3	End of Stop Bit(s) to DE deassertion delay	± 5	

Figure 35 displays the 8-pin Small Outline Integrated Circuit package (SOIC) available for the Z8 Encore! XP F0823 Series devices.



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	1.55	1.73	0.061	0.068
A1	0.10	0.25	0.004	0.010
A2	1.40	1.55	0.055	0.061
B	0.36	0.48	0.014	0.019
C	0.18	0.25	0.007	0.010
D	4.80	4.98	0.189	0.196
E	3.81	3.99	0.150	0.157
e	1.27 BSC		.050 BSC	
H	5.84	6.15	0.230	0.242
h	0.25	0.40	0.010	0.016
L	0.46	0.81	0.018	0.032

CONTROLLING DIMENSIONS : MM
LEADS ARE COPLANAR WITHIN .004 INCH.

Figure 35. 8-Pin Small Outline Integrated Circuit Package (SOIC)

Customer Support

For answers to technical questions about the product, documentation, or any other issues with Zilog's offerings, please visit Zilog's Knowledge Base at http://www.zilog.com/kb.

For any comments, detail technical questions, or reporting problems, please visit Zilog's Technical Support at http://support.zilog.com.